- **Two-Way Asynchronous Communication Between Data Buses**
- **pnp Inputs Reduce dc Loading**
- **Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

SN54ALS243A . . . J PACKAGE
SN74ALS243A . . . D OR N PACKAGE
(TOP VIEW)

$\overline{OEAB}$	1	14	V$_{CC}$
NC	2	13	OEBA
A1	3	12	NC
A2	4	11	B1
A3	5	10	B2
A4	6	9	B3
GND	7	8	B4

SN54ALS243A . . . FK PACKAGE
(TOP VIEW)

Pins (top): NC, $\overline{OEAB}$, NC, V$_{CC}$, OEBA — 3 2 1 20 19

Left: A1 4, NC 5, A2 6, NC 7, A3 8
Right: 18 NC, 17 NC, 16 B1, 15 NC, 14 B2
Bottom: A4 9, GND 10, NC 11, B4 12, B3 13
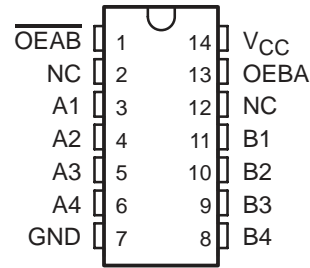
NC – No internal connection

description

These quadruple bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing. These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEBA and $\overline{OEAB}$) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.
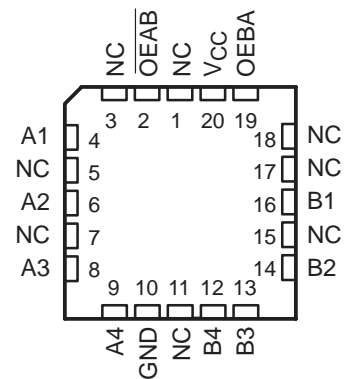
The dual-enable configuration gives the quadruple bus transceivers the capability to store data by simultaneously enabling OEBA and $\overline{OEAB}$. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (eight in all) retain their states. The 4-bit codes appearing on the two sets of buses are identical.

The SN54ALS243A is characterized for operation over the full military temperature range of $-55°$C to $125°$C. The SN74ALS243A is characterized for operation from $0°$C to $70°$C.

FUNCTION TABLE

INPUTS		FUNCTION
$\overline{OEAB}$	OEBA	
L	L	A to B
H	H	B to A
H	L	Isolation
L	H	Latch A and B (A = B)

Copyright © 1994, Texas Instruments Incorporated

TEXAS INSTRUMENTS

logic symbol†

logic diagram (positive logic)
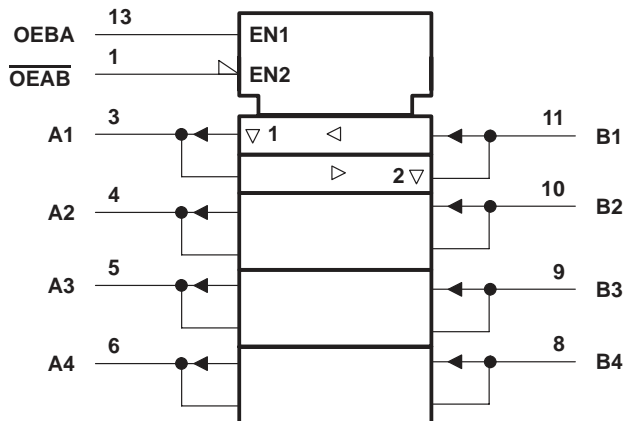
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.
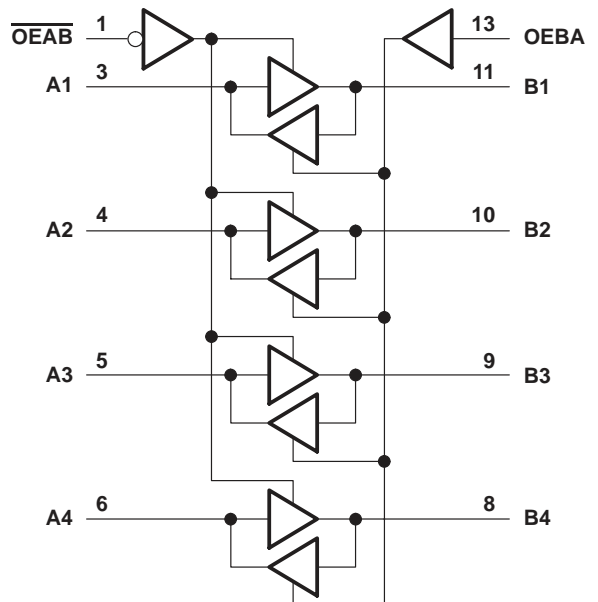
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} . . . . 7 V
Input voltage, V_I: All inputs . . . . 7 V
             I/O ports . . . . 5.5 V
Operating free-air temperature range, T_A: SN54ALS243A . . . . −55°C to 125°C
                                   SN74ALS243A . . . . 0°C to 70°C
Storage temperature range . . . . −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS243A			SN74ALS243A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−12			−15	mA
I_{OL}	Low-level output current			12			24	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

![Texas Instruments logo]

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS243A			SN74ALS243A			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −0.4 mA	V_{CC} −2			V_{CC} −2			V
		V_{CC} = 4.5 V	I_{OH} = −3 mA	2.4	3.2		2.4	3.2		
			I_{OH} = −12 mA	2						
			I_{OH} = −15 mA				2			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 24 mA					0.35	0.5	
I_I	Control inputs	V_{CC} = 5.5 V	V_I = 7 V			0.1			0.1	mA
	A or B ports		V_I = 5.5 V			0.1			0.1	
I_{IH}	Control inputs	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
	A or B ports‡					20			20	
I_{IL}	Control inputs	V_{CC} = 5.5 V,	V_I = 0.4 V			−0.1			−0.1	mA
	A or B ports‡					−0.1			−0.1	
I_O§		V_{CC} = 5.5 V,	V_O = 2.25 V	−20		−112	−30		−112	mA
I_{CC}		V_{CC} = 5.5 V	Outputs high		15	30		15	25	mA
			Outputs low		20	35		20	30	
			Outputs disabled		21	37		21	32	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

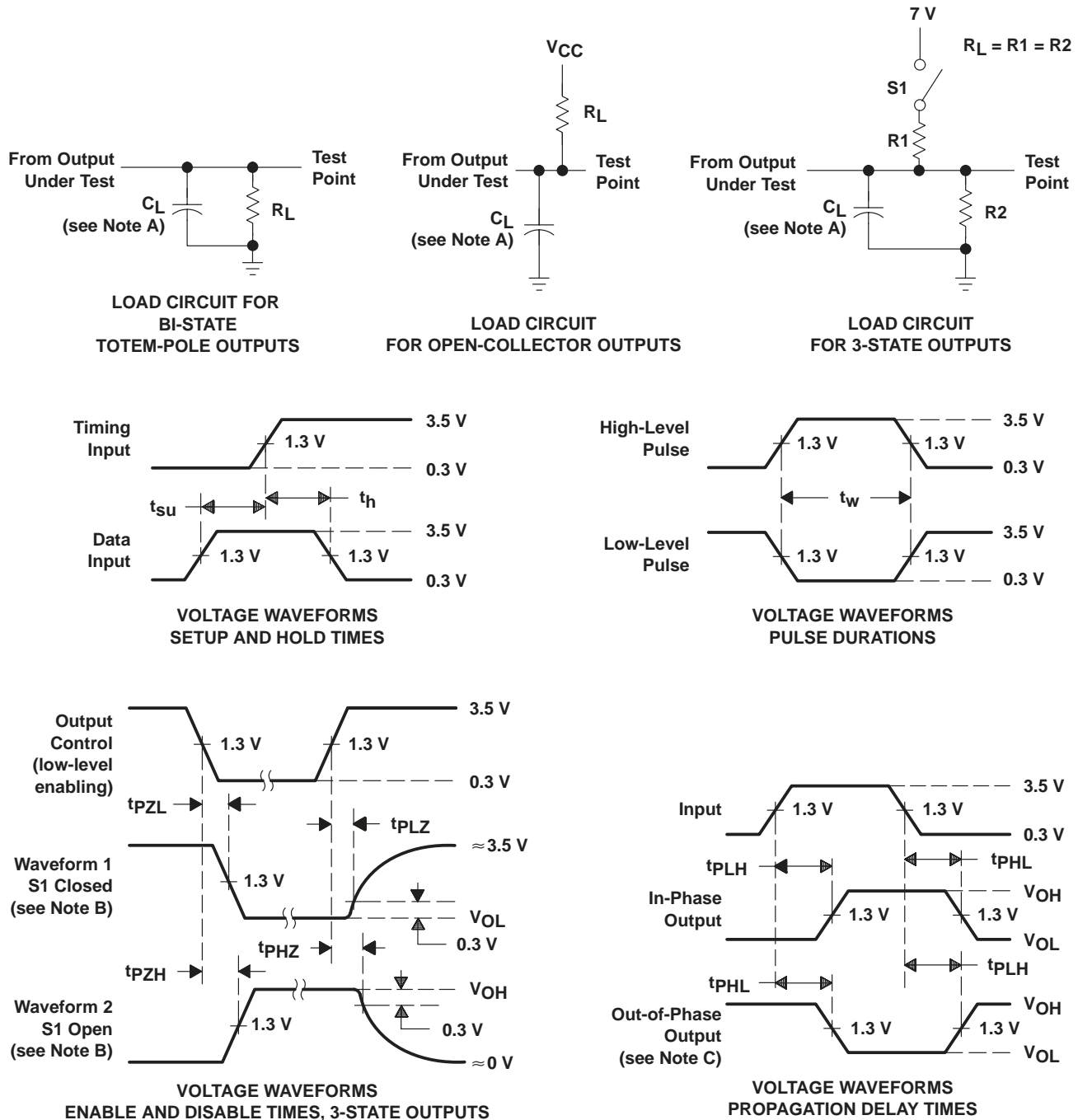| PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX¶				UNIT
			SN54ALS243A		SN74ALS243A		
			MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	4	15	4	11	ns
t_{PHL}			4	15	4	11	
t_{PZH}	$\overline{OEAB}$	B	7	25	7	20	ns
t_{PZL}			7	25	7	20	
t_{PHZ}	$\overline{OEAB}$	B	2	16	2	14	ns
t_{PLZ}			3	27	3	22	
t_{PZH}	OEBA	A	7	25	7	20	ns
t_{PZL}			7	25	7	20	
t_{PHZ}	OEBA	A	2	16	2	14	ns
t_{PLZ}			3	27	3	22	

¶ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

TEXAS
INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES

LOAD CIRCUIT FOR BI-STATE TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS

LOAD CIRCUIT FOR 3-STATE OUTPUTS

$R_L = R1 = R2$

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS PULSE DURATIONS

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
      B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
         Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
      C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
      D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
      E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84013022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84013022A SNJ54ALS 243AFK	Samples
SN74ALS243A-1N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74ALS243AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	ALS243A	
SN74ALS243AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70	SN74ALS243AN	
SN74ALS243ANSR	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI	0 to 70	ALS243A	
SNJ54ALS243AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84013022A SNJ54ALS 243AFK	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS243A, SN74ALS243A :

- Catalog: SN74ALS243A

- Military: SN54ALS243A

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

FK (S−CQCC−N**)
28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS−004

TEXAS INSTRUMENTS
www.ti.com

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

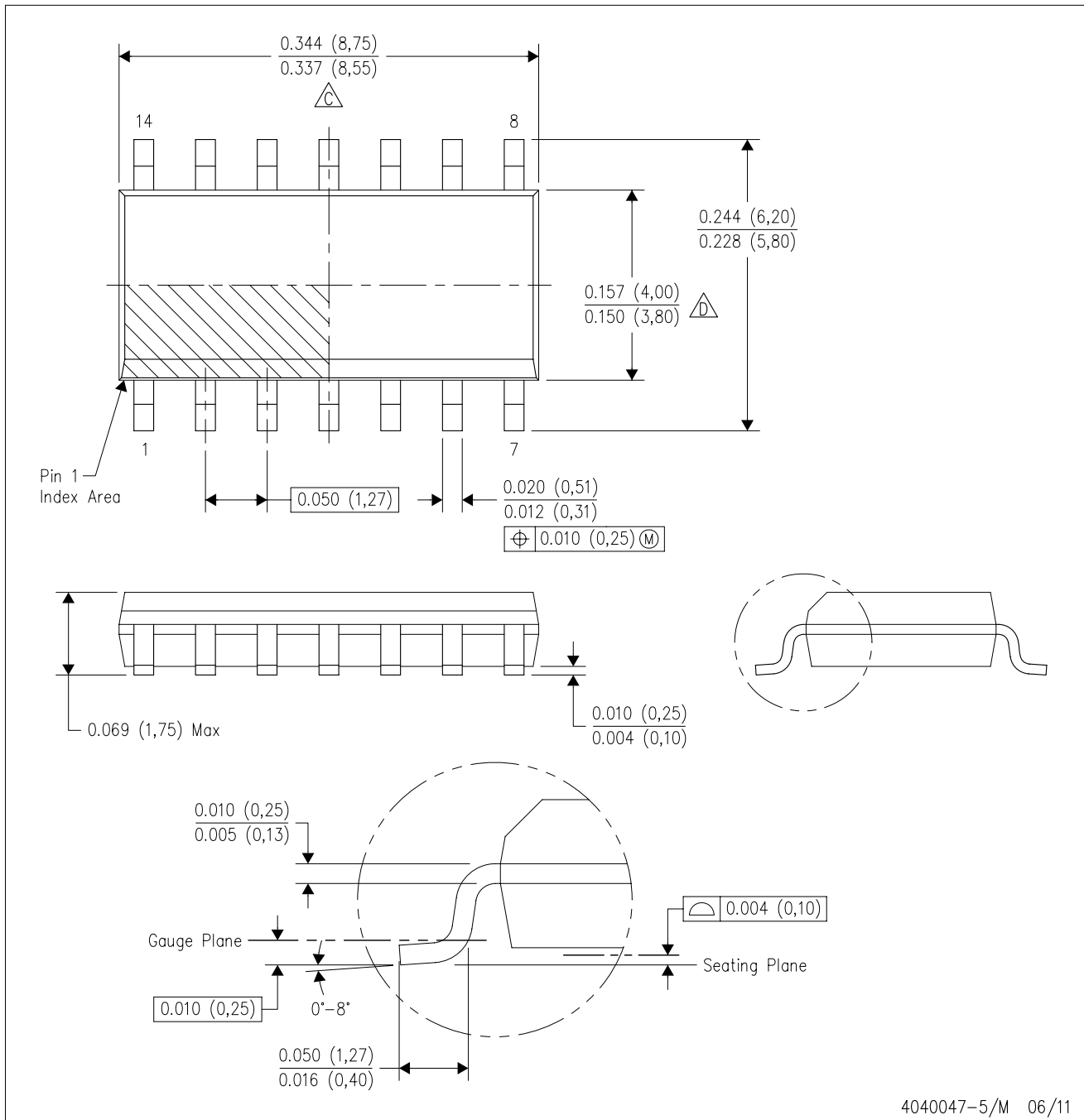| DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R−PDSO−G14) PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
Ⓒ

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) Ⓓ

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°–8°

0.050 (1,27)
0.016 (0,40)

4040047–5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         Ⓒ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
         Ⓓ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E. Reference JEDEC MS–012 variation AB.

TEXAS
INSTRUMENTS
www.ti.com

N (R–PDIP–T**)   PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		